

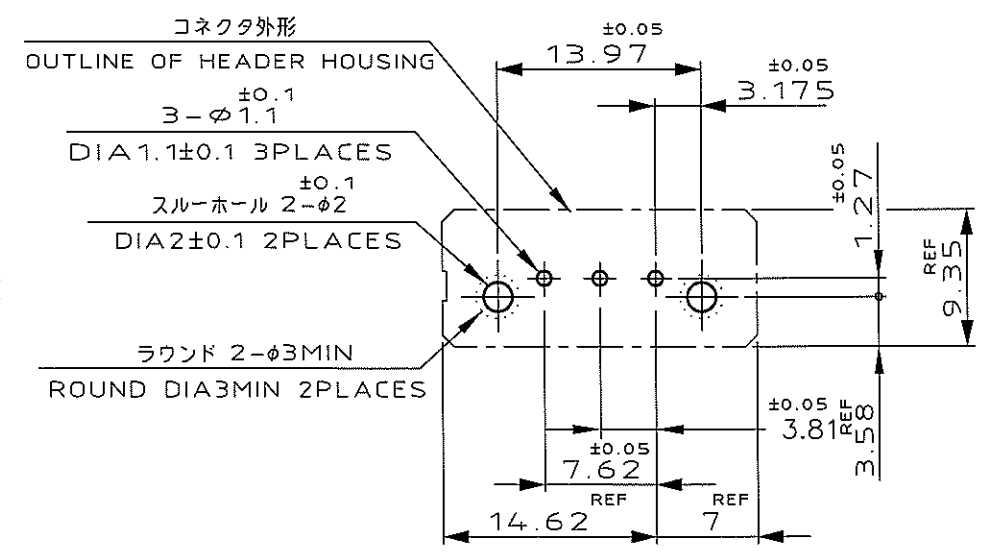
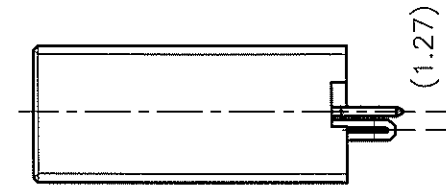
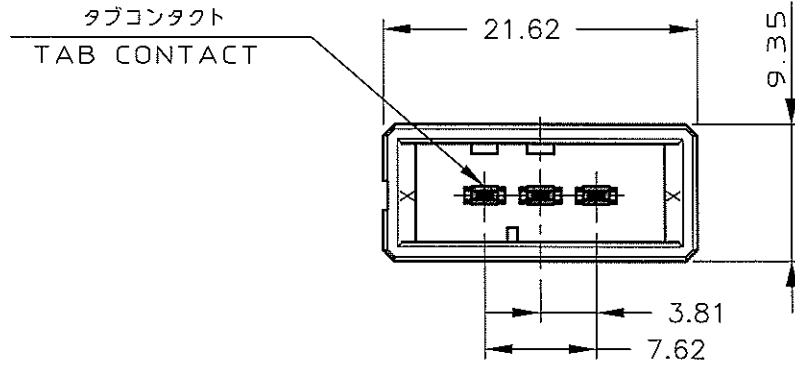
NUMBER 178313



METRIC

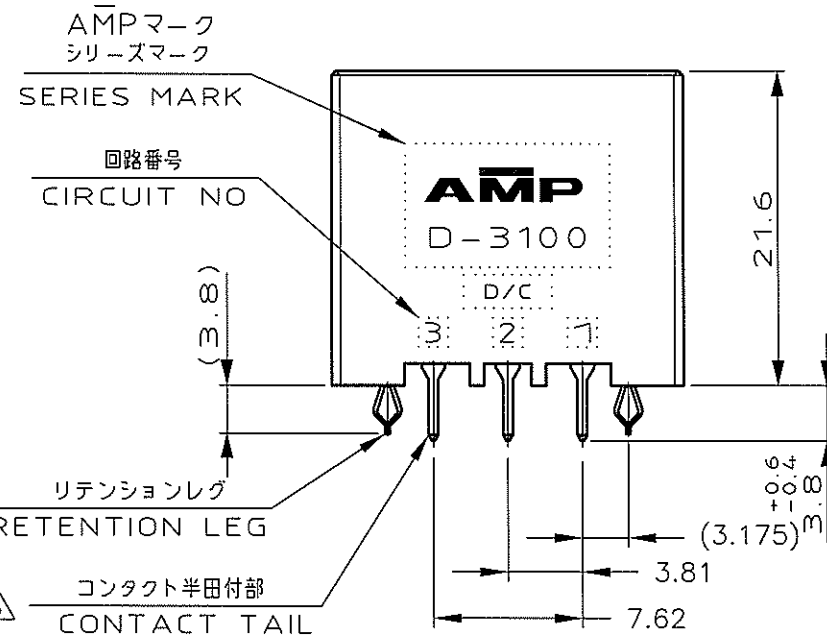
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38µm PdNi & Au PLATING OVER NICKEL
- FINISH (CONTACT AREA): 0.76µm PdNi & Au PLATING OVER NICKEL
- FINISH (CONTACT AREA): 2.0 µm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED
(CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

	Y	BLACK	△6 △4	2-178313-5
		BLACK	△6 △3	2-178313-3
		BLACK	△6 △2	2-178313-2
	X	NATURAL	△6 △4	6-178313-5
		BLACK	△6 △4	1-178313-5
		BLACK	△6 △3	1-178313-3
		BLACK	△6 △2	1-178313-2
キーイング 位置 KEYING LOCATION	キーイング KEYING	ハウジング色 HOUSING COLOR	FINISH	製品番号 PART NO.

						TE TE Connectivity	
WIRE RANGE		INSULATION DIA		NAME			
mm²(AWG -)		mm²		3 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC 3100			
MATERIAL		FINISH		一般公差 (GENERAL TOLERANCE)			
SEE NOTE 注記参照		SEE NOTE 注記参照		SIZE	LOC	NUMBER	
F REVISED PER ECR-25-250788 F.Z R.B 16 JAN 2025		DR. N. Matsubara 18 JUN 91		10% ±0.3	A3	J	C-178313
E1 REVISED PER ECO-11-005030 RK HMR 14 APR 11		DE. N. Matsubara 18 JUN 91		10% ±0.4	SCALE		
LTR REVISION RECORD DR CHK DATE		CHK. S. MANABE 20 APR 94		2-1		REV. F	SHEET 1 OF 1
		APP. S. MANABE 20 APR 94					